RICOH

Step-up DC/DC converter for White LED Backlight

NO.EA-166-170620

OUTLINE

The R1218x Series are PWM control type step-up DC/DC converter ICs with low supply current.

The R1218x is fully dedicated to drive White LED with constant current. Each of these ICs consists of an NMOS FET, an oscillator, a PWM comparator, a voltage reference unit, an error amplifier, a current limit circuit, an under voltage lockout circuit (UVLO), an over-voltage protection circuit (OVP).

The R1218x can drive white LEDs with high efficiency with low supply current. A diode is built-in the R1218xxx1A, therefore it is possible to drive up to 4LEDs without an external diode. The R1218xxx2A, an external diode is necessary, however, up to 7 serial LEDs can be driven with the R1218xxx2A.

Constant current can be set with an external resistance value. Dimming control is possible by PWM signal for CE pin. Feedback voltage is 0.2V, therefore power loss by current setting resistor is small and efficiency is good. Maximum duty cycle is internally fixed, Typ. 91% to 92%. LEDs can be driven from low voltage. Protection circuits are the current limit of Lx peak current, the over voltage limit of output, and the under voltage lockout function.

Packages are standard SOT-23-6 and very tiny DFN(PLP)1820-6.

FEATURES

- Input voltage......1.8V to 5.5V
- Built-in 400mA, 1.5 Ω , 20V Nch MOSFET and diode (R1218xxx1A)
- Built-in 400mA, 1.5Ω, 33V Nch MOSFET (R1218xxx2A)
- Oscillator Frequency (PWM control).....1.2MHz
- Maximum Duty Cycle Typ. 91% to 92%
- Feedback Voltage Typ. 0.2V
- UVLO Threshold Voltage Typ. 1.6V (Hysteresis Typ. 0.1V)
- Lx Current limit Protection...... Typ. 700mA
- Over Voltage Protection (OVP) Threshold.... Typ. 9.5V (R1218x021A)
 - Typ. 14.0V (R1218x031A)
 - Typ. 18.5V (R1218x041A)
 - Typ. 23.0V (R1218x052A)
 - Typ. 27.5V (R1218x062A)
 - Typ. 31.5V (R1218x072A)

| • | LED dimming controlby | / external PWM signal (Frequency 200Hz to 5kHz) to CE pi |
|---|-----------------------|--|
| | by f | / feedback voltage and filtered PWM signal (high frequency |
| • | PackagesDFI | FN(PLP)1820-6, SOT-23-6 |

APPLICATIONS

• White LED Backlight for portable equipment

NO.EA-166-170620

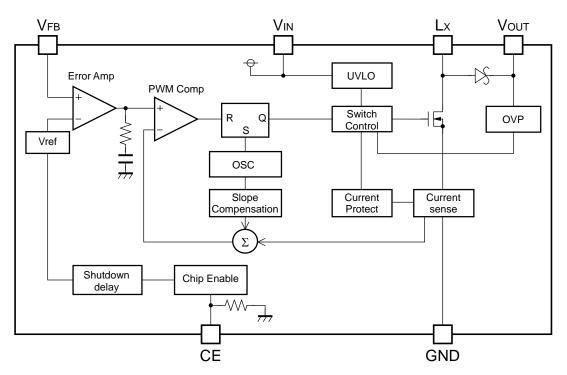
SELECTION GUIDE

The OVP threshold, the built-in diode, and the package for the ICs can be selected at the user's request.

| Product Name | | Package | Quantity | per Reel | Pb Free | Halogen Free |
|------------------|------------------------|--------------------------|------------------|---------------|-------------------|--------------|
| R1218Kxxxx-TR | | DFN(PLP)1820-6 | 5,000 |) pcs | Yes | Yes |
| R1218Nxxxx-TR-FE | | SOT-23-6 | 3,000 |) pcs | Yes | Yes |
| xxxx: | The combination of the | e OVP threshold and with | h/without of | built-in dioc | le can be designa | ated. |
| | Code | OVP Thresh | OVP Threshold Bu | | It-in Diode | |
| | 021A | 9.5V | 9.5V | | Yes | |
| | 031A | 14.0V | 14.0V | | Yes | |
| | 041A | 18.5V | 18.5V | | Yes | |
| | 052A | 23.0V | 23.0V | | No | |
| | 062A 27.5V | | | | No | |
| | 072A 31.5V | | | No | | |

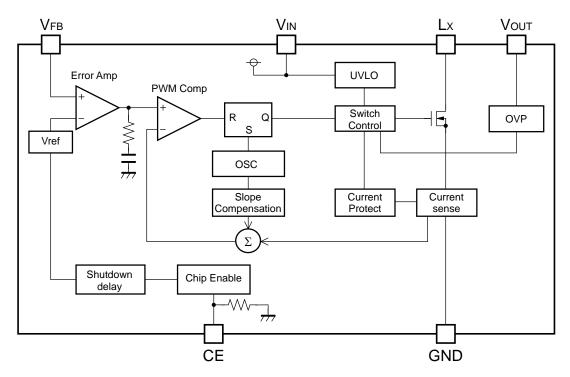
R1218x NO.EA-166-170620

BLOCK DIAGRAMS



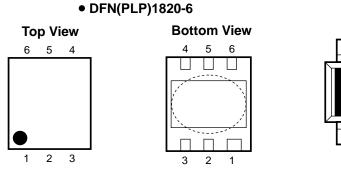
R1218xxx1A

R1218xxx2A

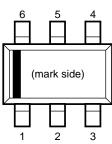


NO.EA-166-170620

PIN DESCRIPTIONS



• SOT-23-6



• DFN(PLP)1820-6

| Pin No | Symbol | Pin Description |
|--------|--------|--------------------------------------|
| 1 | CE | Chip Enable Pin ("H" Active) |
| 2 | Vfb | Feedback Pin |
| 3 | Lx | Switching Pin (Open Drain Output) |
| 4 | GND | Ground Pin |
| 5 | Vin | Power Supply Input Pin |
| 6 | Vout | Output Pin |

*) Tab is GND level. (They are connected to the reverse side of this IC.)

The tab is better to be connected to the GND, but leaving it open is also acceptable.

• SOT-23-6

| Pin No | Symbol | Pin Description |
|--------|--------|-----------------------------------|
| 1 | CE | Chip Enable Pin ("H" Active) |
| 2 | Vout | Output Pin |
| 3 | Vin | Power Supply Input Pin |
| 4 | Lx | Switching Pin (Open Drain Output) |
| 5 | GND | Ground Pin |
| 6 | Vfb | Feedback Pin |

(GND=0V)

NO.EA-166-170620

ABSOLUTE MAXIMUM RATINGS

| Symbol | | Item | Rating | Unit |
|--------|-----------------------------|-------------------------------------|-----------------|------|
| VIN | V _{IN} Pin Voltage | | 6.5 | V |
| Vce | CE Pin Voltage | | -0.3 to VIN+0.3 | V |
| Vfb | VFB Pin Voltage | | -0.3 to VIN+0.3 | V |
| N/ | | R1218xxx1A | -0.3 to 22 | V |
| Vout | Vout Pin Voltage | R1218xxx2A | -0.3 to 34 | V |
| N/ | | R1218xxx1A | -0.3 to 22 | v |
| Vlx | Lx Pin Voltage | R1218xxx2A | -0.3 to 34 | V |
| ILX | Lx Pin Current | | 1000 | mA |
| 5 | Power Dissipation (D | Power Dissipation (DFN(PLP)1820-6)* | | 10/ |
| PD | Power Dissipation (S | OT-23-6)* | 420 | mW |
| Tj | Junction Temperature Range | | -40 to 125 | °C |
| Tstg | Storage Temperature Range | | -55 to 125 | °C |

*) For Power Dissipation, please refer to PACKAGE INFORMATION.

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS

| Symbol | ltem | Rating | Unit |
|--------|-----------------------------|------------|------|
| VIN | Operating Input Voltage | 1.8 to 5.5 | V |
| Та | Operating Temperature Range | -40 to 85 | °C |

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

NO.EA-166-170620

ELECTRICAL CHARACTERISTICS

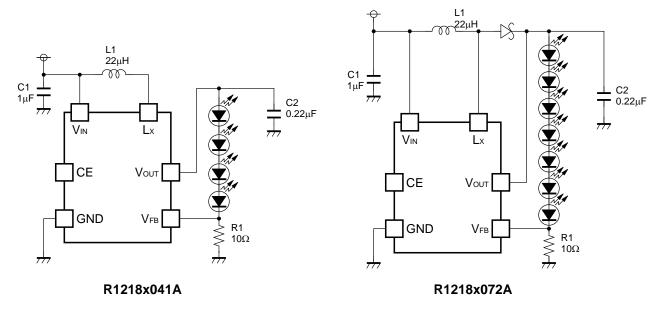
• R1218xxxxA

Ta=25°C

| Symbol | ltem | Cone | ditions | Min. | Тур. | Max. | Unit | |
|--------------|--|-------------------------|------------------|------|------------|------|------------|--|
| DD | Supply Current | VIN=5.5V, VFB=0 | V, Lx at no load | | 0.5 | 1.0 | mA | |
| Istandby | Standby Current | VIN=5.5V, VCE=0V | | | 0 | 3.0 | μA | |
| VUVLO1 | UVLO Detector Threshold | V _{IN} falling | | 1.5 | 1.6 | 1.7 | V | |
| VUVLO2 | UVLO Released Voltage | V _{IN} rising | | | VUVLO1+0.1 | 1.8 | V | |
| VCEH | CE Input Voltage "H" | VIN=5.5V | | 1.5 | | | V | |
| Vcel | CE Input Voltage "L" | VIN=1.8V | | | | 0.5 | V | |
| RCE | CE Pull Down Resistance | VIN=3.6V | | 600 | 1200 | 2200 | kΩ | |
| tshtdn | CE Shutdown Delay Time | VIN=3.6V | | | 10 | | ms | |
| Vfb | V _{FB} Voltage | VIN=3.6V | | 0.19 | 0.20 | 0.21 | V | |
| ∆Vғв/ ∆Та | VFB Voltage Temperature Coefficient | Vin=3.6V, -40°C | s ≤ Ta ≤ 85°C | | ±150 | | ppm /°C | |
| Ігв | VFB Input Current | VIN=5.5V, VFB=0 | V or 5.5V | -0.1 | | 0.1 | μA | |
| Ron | Switch On Resistance | VIN=3.6V, Isw=100mA | | | 1.5 | | Ω | |
| | | R1218xxx1A | VLX=20V | | 0 | 3.0 | μA | |
| LXleak | Switch Leakage Current | R1218xxx2A VLX=29V | | | 0 | 3.0 | μA | |
| LXlim | Switch Current Limit | VIN=3.6V | | 400 | 700 | 1000 | mA | |
| Vf | Diode Forward Voltage | R1218xxx1A IDIODE=100mA | | | 0.8 | | V | |
| DIODEleak | Diode Leakage Current | R1218xxx1A | Vout=20V, Vlx=0V | | 10 | | μA | |
| fosc | Oscillator Frequency | VIN=3.6V, VOUT= | Vfb=0V | 1.0 | 1.2 | 1.4 | MHz | |
| Movduty | Movimum Duty Cycle | VIN=3.6V, | R1218x072A | 86 | 92 | | 0/ | |
| Maxouty | Maximum Duty Cycle | Vout=Vfb=0V | Others | 86 | 91 | | % | |
| | | | R1218x021A | 8.5 | 9.5 | 10.5 | - V | |
| | | | R1218x031A | 13.0 | 14.0 | 15.0 | | |
| Maria | | Vin=3.6V, | R1218x041A | 17.0 | 18.5 | 20.0 | | |
| Vovp1 | OVP Detector Threshold | Vout rising | R1218x052A | 21.5 | 23.0 | 24.5 | | |
| | | | R1218x062A | 26.0 | 27.5 | 29.0 | | |
| | | | R1218x072A | 30.0 | 31.5 | 33.0 | | |
| | | | R1218x021A | | Vovp1-0.5 | | | |
| | | | R1218x031A | | Vovp1-0.75 | | | |
| N/ | | VIN=3.6V, | R1218x041A | | Vovp1-1.0 | | | |
| Vovp2 | OVP Released Voltage | Vout falling | R1218x052A | | Vovp1-1.25 | | - V | |
| | | | R1218x062A | | Vovp1-1.5 | | | |
| | | R1218x072A | | | Vovp1-1.75 | |] | |

APPLICATION INFORMATION

• Typical Application Circuit



• LED Current setting

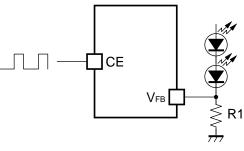
LED current can be set with feedback resistor(R1) $I_{\text{LED}}{=}0.2 \ / \ \text{R1}$

• LED Dimming Control, Softstart

(1) LED dimming control by PWM signal to CE pin

LED dimming control is possible by forcing PWM signal to CE pin.

When the power-on or start up with CE pin, softstart function works, however, after that, if the CE pin is set as "L" and set CE pin "H" again during the shutdown delay time, softstart function is disabled and starts up fast to normal mode, therefore 200Hz to 5kHz PWM signal is standard. By the CE pin input, LED turns on and off. Average LED current varies depending on the duty cycle of CE input. Too high frequency PWM signal is not effective because of its delay.



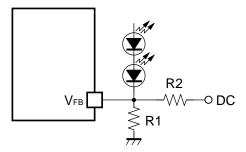
Dimming control by CE pin input

NO.EA-166-170620

(2) Dimming control by DC voltage

LED dimming control is also possible by using the DC voltage to VFB pin. LED current is adjustable by DC voltage and resistors, R1 and R2 in the following figure.

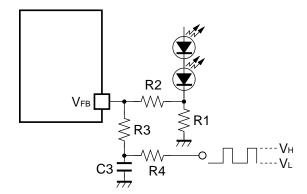
 $I_{LED}=(DC - 0.2) / R2 - 0.2 / R1$



Dimming control by DC voltage

(3) Dimming control by feedback voltage and filtered PWM signal

LED dimming control is also possible by using the feedback voltage and filtered PWM signal. LED current is adjustable according to the "H" level (V_H) and "L" level(V_L) of PWM signal and resistors, R1, R2, R3, and R4 in the following figure.



Dimming control by filtered PWM signal

Duty=0% to 100% PWM signal duty cycle can be used up to the maximum LED current and minimum LED current as in the next formulas.

 $I_{LEDMIN} = \{0.2 - R2 \times (V_H - 0.2) / (R3 + R4)\} / R1$ $I_{LEDMAX} = \{0.2 - R2 \times (V_L - 0.2) / (R3 + R4)\} / R1$

For example, supposed that the PWM signal level is set as 2.5V/0V, to adjust the LED current range from 0mA to 20mA by the duty cycle, our recommendation external components values are, R1=10Ω, R2=5.1kΩ, R3=51k Ω , R4=5.1k Ω or around.

C3 should be set large enough to regard the PWM signal as adjustable DC voltage by the filter. In this method, higher frequency control than the frequency against the CE pin can be used for dimming control. For example, if the frequency is 40kHz, 0.1µF or more capacitor is our recommendation value as C3.

Selection of Inductors

The peak current of the inductor at normal mode can be calculated as next formula: $I_{LX}peak=1.25 \times I_{LED} \times V_{OUT} / V_{IN} + 0.5 \times V_{IN} \times (V_{OUT} - V_{IN}) / (L \times V_{OUT} \times fosc)$

When the start-up or dimming control by CE pin, transient current flows, the peak current must be equal or less than the current limit of the IC. The peak current should not beyond the rating current of the inductor. For example, for 4 serial LED drive from V_{IN} =3.6V, recommendation value of the inductor is 22µH or more.

• Selection of Capacitors

Set 1μ F or more value bypass capacitor C1 between V_{IN} pin and GND pin as close as posible. Set 0.22μ F or more capacitor C2 between V_{OUT} and GND pin.

TECHNICAL NOTES

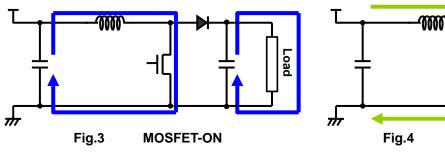
Current path on PCB

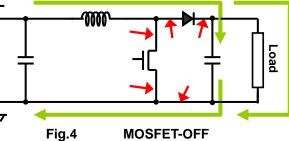
The current paths in an application circuit are shown in Fig.3 and 4.

A current flows through the paths shown in Fig.3 at the time of MOSFET-ON, and shown in Fig.4 at the time of MOSFET-OFF. In the paths pointed with red arrows in Fig.4, current flows just in MOSFET-ON period or just in MOSFET-OFF period. Parasitic impedance / inductance and the capacitance of these paths influence stability of the system and cause noise outbreak. So please minimize this side effect. In addition, please shorten the wiring of other current paths shown in Fig.3 and 4 except for the paths of LED load.

●LAYOUT Guide for PCB

- Please shorten the wiring of the input capacitor (C1) between V_{IN} pin and GND pin of IC. The GND pin should be connected to the strong GND plane.
- \cdot The area of Lx land pattern should be smaller.
- In the case of internal diode version, please put output capacitor (C2) close to the Vout pin.
- In the case of external diode, the wiring between Lx pin and inductor and diode should be short and please put output capacitor(C2) close to the cathode of diode.
- · Please make the GND side of output capacitor (C2) close to the GND pin of IC.



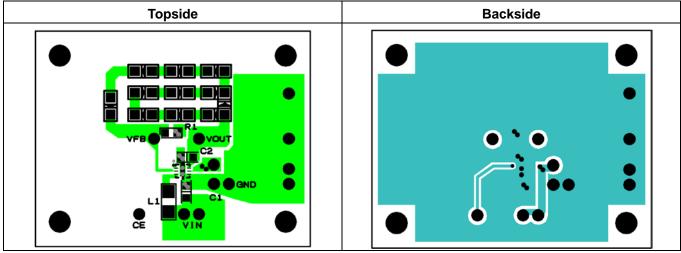


NO.EA-166-170620

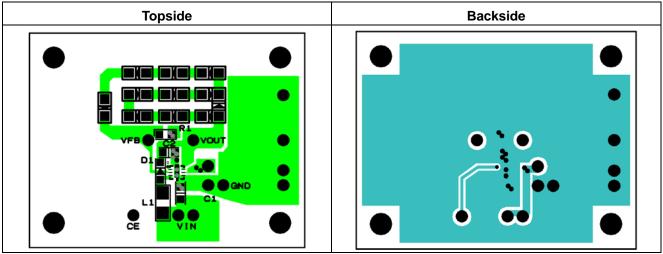
PCB Layout

• PKG: DFN(PLP)1820-6pin

R1218Kxx1A

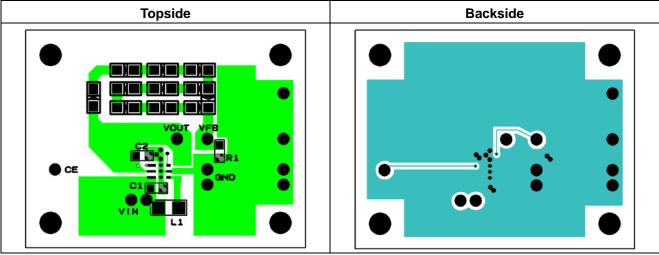


R1218Kxx2A

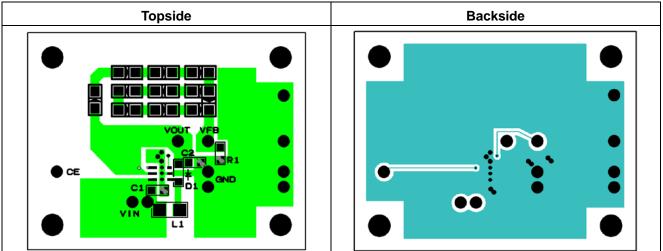


• PKG: SOT-23-6pin

R1218Nxx1A



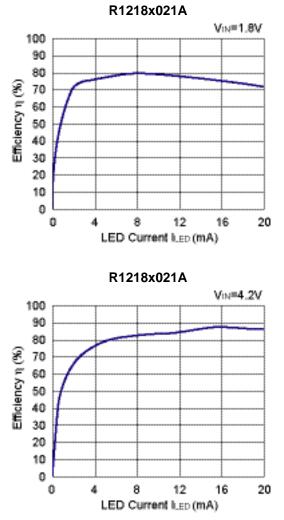
R1218Nxx2A

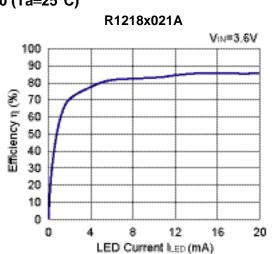


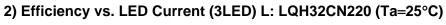
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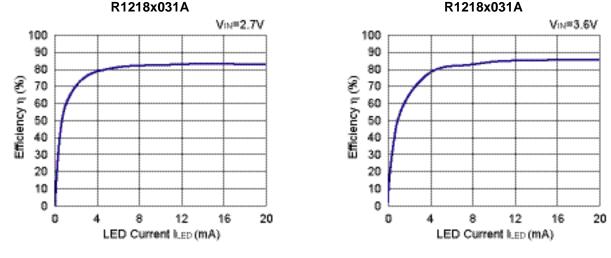
TYPICAL CHARACTERISTICS

1) Efficiency vs. LED Current (2LED) L:LQH32CN220 (Ta=25°C)



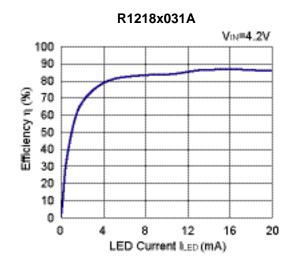




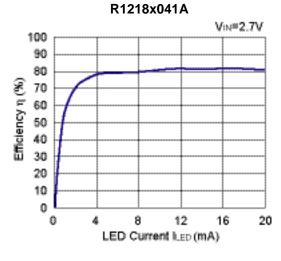


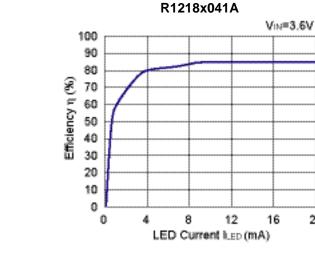
R1218x NO.EA-166-170620

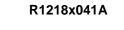
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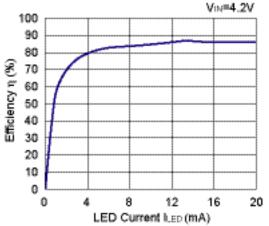


3) Efficiency vs. LED Current (4LED) L: LQH32CN220 (Ta=25°C)

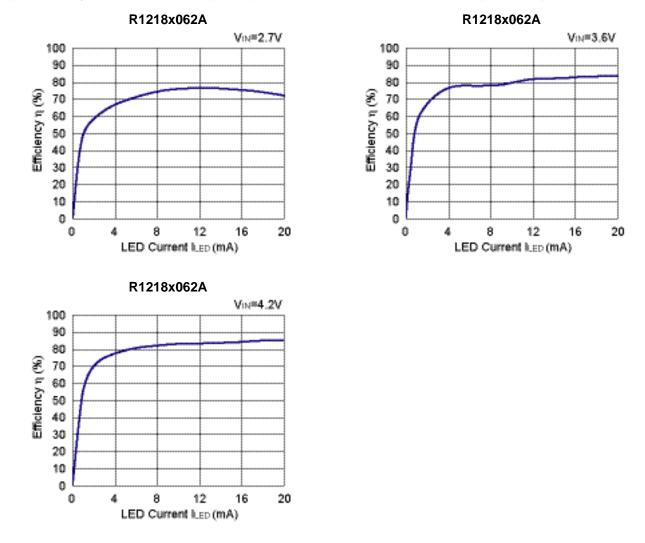




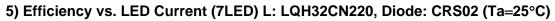


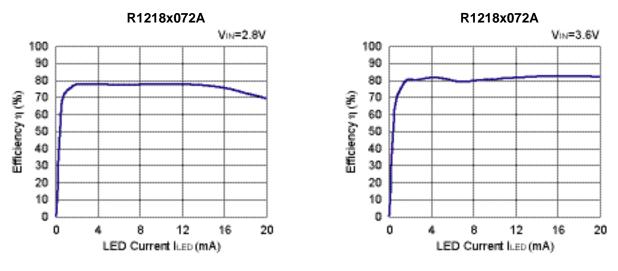


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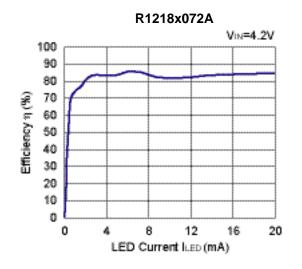
4) Efficiency vs. LED Current (6LED) L: LQH32CN220, Diode: CRS02 (Ta=25°C)



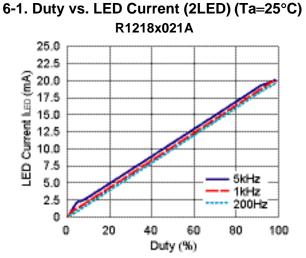


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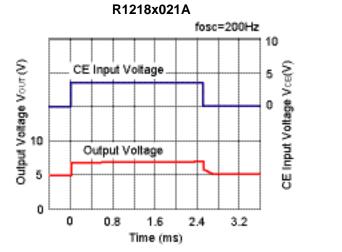
R1218x NO.EA-166-170620

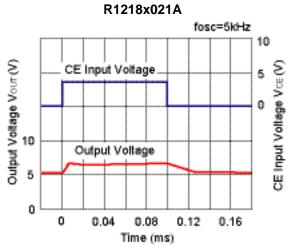


6) PWM Dimming Control (2LED) $V_{IN}=3.6V$, R1=10 Ω



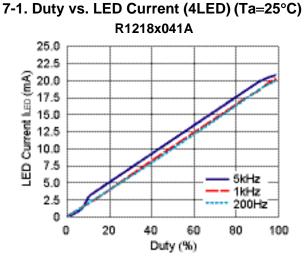
6-2. Output Voltage Waveform (2LED) (Ta=25°C)



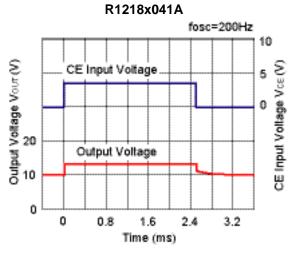


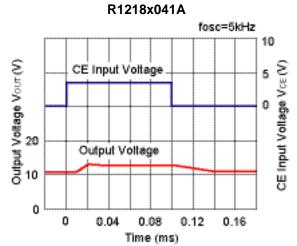
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7) PWM Dimming Control (4LED) VIN=3.6V, R1=10 Ω

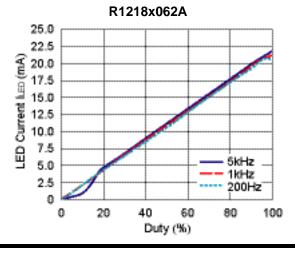




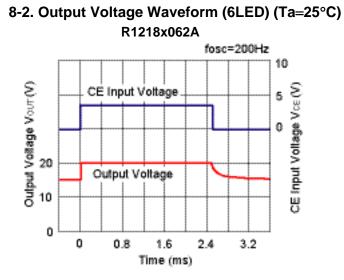


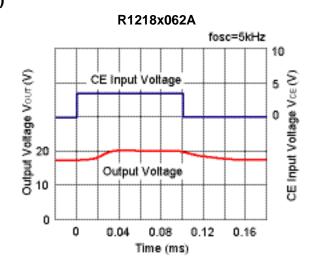


8) PWM Dimming Control (6LED) V_{IN}=3.6V, R1=10Ω
 8-1. Duty vs. LED Current (6LED) (Ta=25°C)

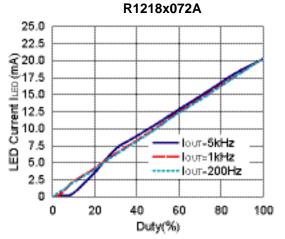


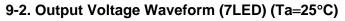
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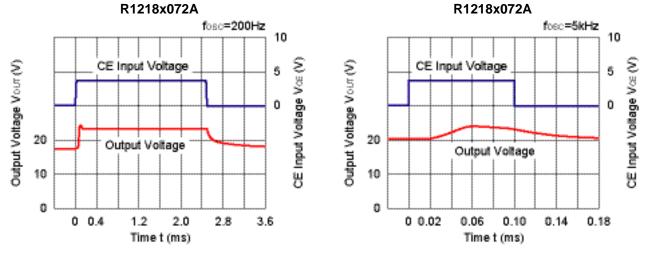




9) PWM Dimming Control (7LED) VIN=3.6V, R1=10Ω
9-1. Duty vs. LED Current (7LED) (Ta=25°C)



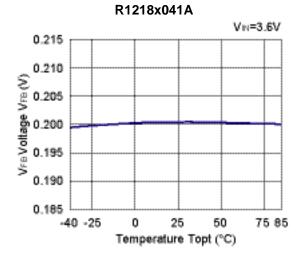


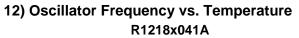


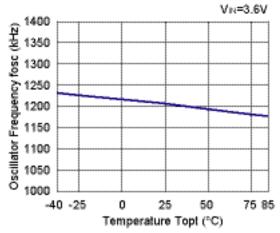
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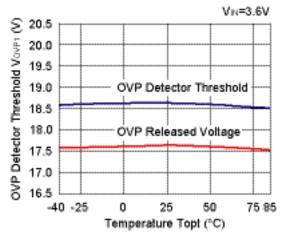
10) VFB Voltage vs. Temperature

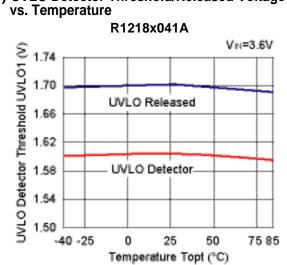






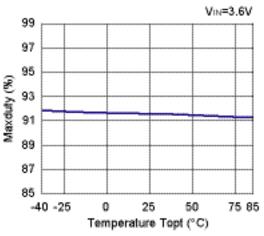


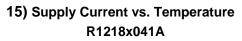


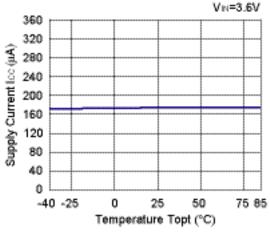


11) UVLO Detector Threshold/Released Voltage

13) Maximum duty cycle vs. Temperature R1218x041A



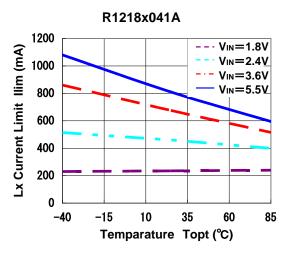




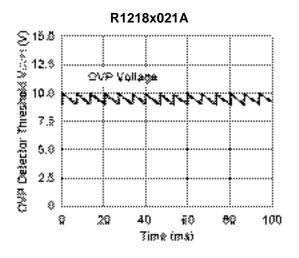
RICOH

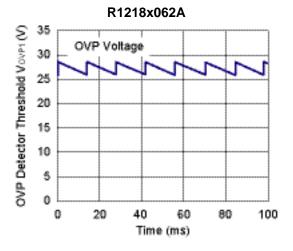
R1218x NO.EA-166-170620

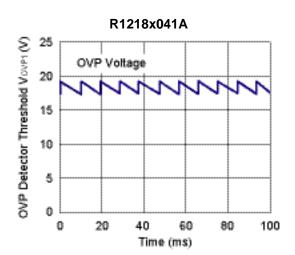
16) Lx Current Limit vs. Temperature



17) OVP Transient Response (Ta=25°C)

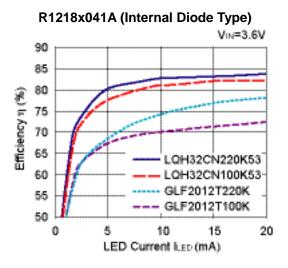






NO.EA-166-170620

18) Efficiency dependence on inductors (4 LED)



POWER DISSIPATION

DFN(PLP)1820-6

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

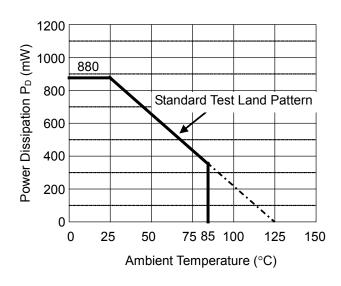
Measurement Conditions

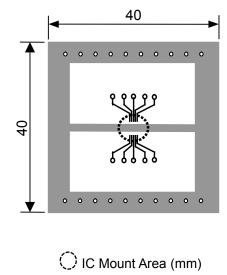
| | Standard Test Land Pattern |
|------------------|--|
| Environment | Mounting on Board (Wind Velocity = 0 m/s) |
| Board Material | Glass Cloth Epoxy Plastic (Double-Sided Board) |
| Board Dimensions | 40 mm × 40 mm × 1.6 mm |
| Connor Potio | Top Side: Approx. 50% |
| Copper Ratio | Bottom Side: Approx. 50% |
| Through-holes | φ 0.54 mm × 30 pcs |

Measurement Result

(Ta = 25°C, Tjmax = 125°C)

| | Standard Test Land Pattern | |
|--------------------|---------------------------------------|--|
| Power Dissipation | 880 mW | |
| Thermal Resistance | θja = (125 – 25°C) / 0.88 W = 114°C/W | |





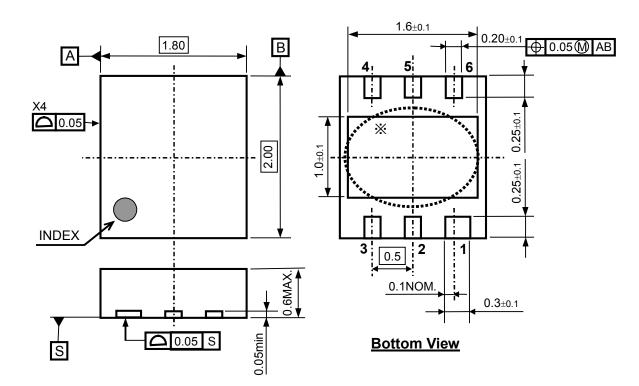
Power Dissipation vs. Ambient Temperature

Measurement Board Pattern

PACKAGE DIMENSIONS

DFN(PLP)1820-6

Ver. A



DFN(PLP)1820-6 Package Dimensions (Unit: mm)

^{*} The tab on the bottom of the package is substrate level (GND). It is recommended that the tab be connected to the ground plane on the board, or otherwise be left floating.



POWER DISSIPATION

SOT-23-6

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

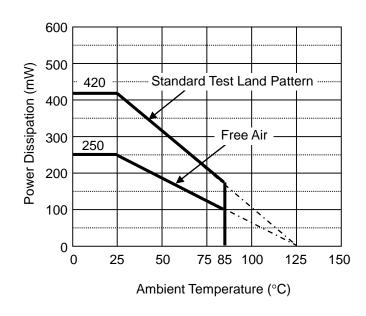
Measurement Conditions

| | Standard Test Land Pattern |
|------------------|--|
| Environment | Mounting on Board (Wind Velocity = 0 m/s) |
| Board Material | Glass Cloth Epoxy Plastic (Double-Sided Board) |
| Board Dimensions | 40 mm x 40 mm x 1.6 mm |
| Copper Ratio | Top Side: Approx.50% Bottom Side: Approx. 50% |
| Through-holes | φ 0.5 mm x 44 pcs |

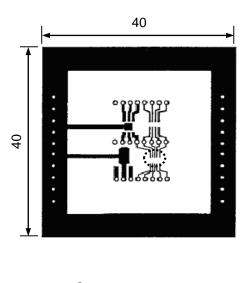
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

| | Standard Test Land Pattern | Free Air |
|--------------------|---------------------------------------|----------|
| Power Dissipation | 420 mW | 250 mW |
| Thermal Resistance | θja = (125 - 25°C) / 0.42 W = 238°C/W | 400°C/W |



| Power Dissipati | on vs. Ambient | Temperature |
|------------------------|----------------|-------------|
|------------------------|----------------|-------------|



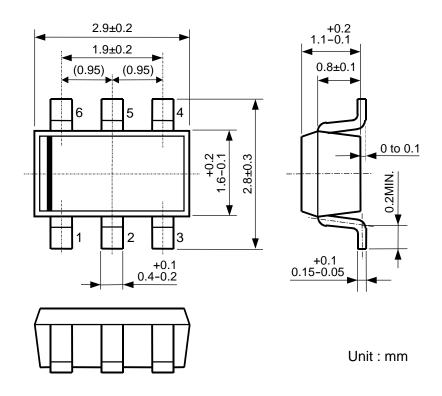
() IC Mount Area (mm)

Measurement Board Pattern

PACKAGE DIMENSIONS

SOT-23-6

Ver. A





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Ricoh is committed to reducing the environmental loading materials in electrical devices with a view to contributing to the protection of human health and the environment. Ricoh has been providing RoHS compliant products since April 1, 2006 and Halogen-free products since April 1, 2012.

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